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#### Applications of "[Embedded - Microcontrollers](#)"

##### Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	29
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-WFQFN Exposed Pad
Supplier Device Package	-
Purchase URL	<a href="https://www.e-xfl.com/product-detail/nuvoton-technology-corporation-america/mini54zan">https://www.e-xfl.com/product-detail/nuvoton-technology-corporation-america/mini54zan</a>

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## 3.2 PIN CONFIGURATION

### 3.2.1 LQFP 48-pin

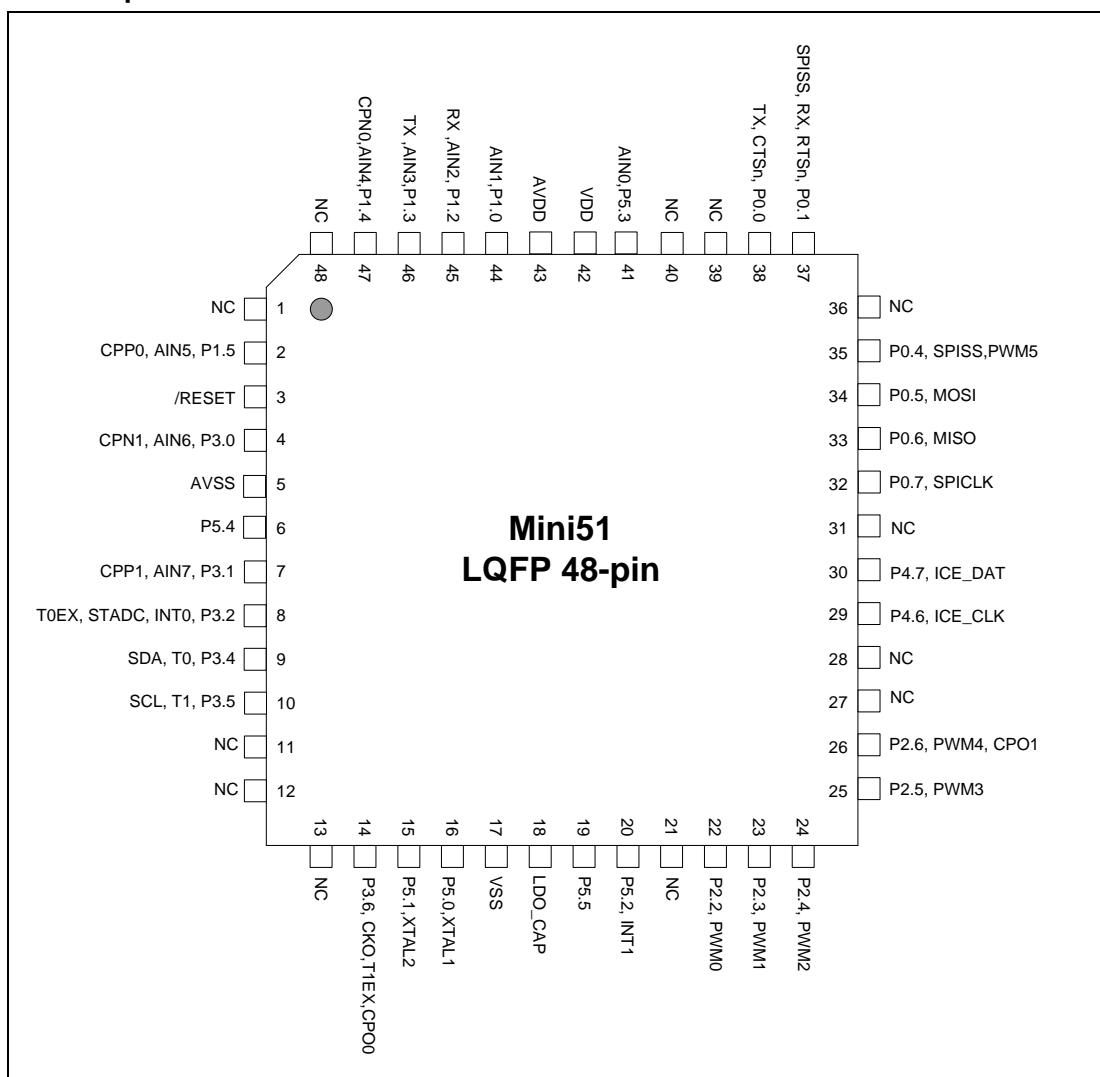


Figure 3.2-1 NuMicro Mini51™ Series LQFP 48-pin Assignment

### 3.3 Pin Description

Pin Number		Pin Name	Pin Type	Description
LQFP 48-pin	QFN 33-pin			
1		NC		Not connected
2	1	P1.5	I/O	Digital GPIO pin
		AIN5	AI	ADC analog input pin
		CPP0	AI	Analog comparator Positive input pin
3	2	/RESET	I(ST)	The Schmitt trigger input pin for hardware device reset. A “Low” on this pin for 768 clock counter of Internal RC 22.1184 MHz while the system clock is running will reset the device. /RESET pin has an internal pull-up resistor allowing power-on reset by simply connecting an external capacitor to GND.
4	3	P3.0	I/O	Digital GPIO pin
		AIN6	AI	ADC analog input pin
		CPN1	AI	Analog comparator negative input pin
5		AVSS	AP	Ground pin for analog circuit
6	4	P5.4	I/O	Digital GPIO pin
7	5	P3.1	I/O	Digital GPIO pin
		AIN7	AI	ADC analog input pin
		CPP1	AI	Analog comparator positive input pin
8	6	P3.2	I/O	Digital GPIO pin
		INT0	I	External interrupt 0 input pin
		STADC	I	ADC external trigger input pin
		T0EX	I	Timer 0 external capture/reset trigger input pin
9	7	P3.4	I/O	Digital GPIO pin
		T0	I/O	Timer 0 external event counter input pin
		SDA	I/O	I <sup>2</sup> C data I/O pin
10	8	P3.5	I/O	Digital GPIO pin
		T1	I/O	Timer 1 external event counter input pin
		SCL	I/O	I <sup>2</sup> C clock I/O pin
11		NC		Not connected
12		NC		Not connected
13		NC		Not connected

## 4 BLOCK DIAGRAM

### 4.1 NuMicro Mini51™ Block Diagram

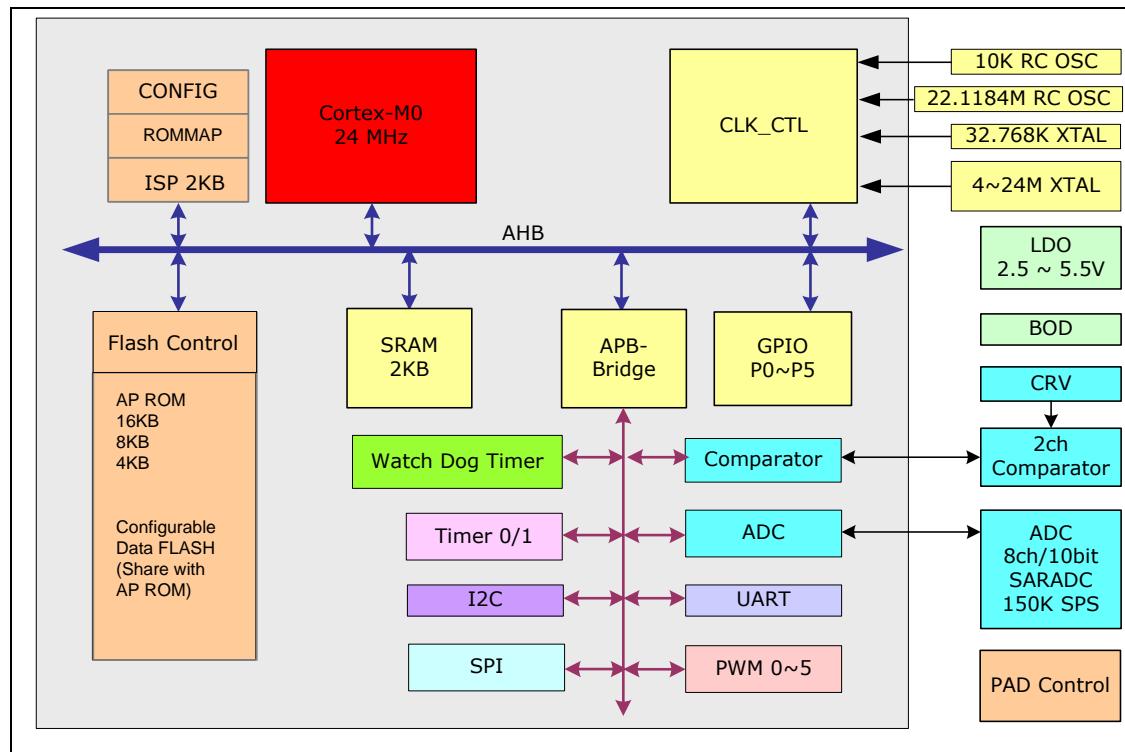


Figure 4.1-1 NuMicro Mini51™ Series Block Diagram

### 5.1.2 System Memory Map

The memory locations assigned to each on-chip controllers are shown in the following table.

Address Space	Token	Controllers
<b>Flash and SRAM Memory Space</b>		
0x0000_0000 – 0x0000_3FFF	FLASH_BA	Flash Memory Space (16 KB)
0x2000_0000 – 0x2000_07FF	SRAM_BA	SRAM Memory Space (2 KB)
<b>AHB Controllers Space (0x5000_0000 – 0x501F_FFFF)</b>		
0x5000_0000 – 0x5000_01FF	GCR_BA	Global Control Registers
0x5000_0200 – 0x5000_02FF	CLK_BA	Clock Control Registers
0x5000_0300 – 0x5000_03FF	INT_BA	Interrupt Multiplexer Control Registers
0x5000_4000 – 0x5000_7FFF	GP_BA	GPIO Control Registers
0x5000_C000 – 0x5000_FFFF	FMC_BA	Flash Memory Control Registers
<b>APB1 Controllers Space (0x4000_0000 – 0x401F_FFFF)</b>		
0x4000_4000 – 0x4000_7FFF	WDT_BA	Watchdog Timer Control Registers
0x4001_0000 – 0x4001_3FFF	TMR_BA	Timer0/Timer1 Control Registers
0x4002_0000 – 0x4002_3FFF	I2C_BA	I <sup>2</sup> C Interface Control Registers
0x4003_0000 – 0x4003_3FFF	SPI_BA	SPI Control Registers
0x4004_0000 – 0x4004_3FFF	PWM_BA	PWM Control Registers
0x4005_0000 – 0x4005_3FFF	UART_BA	UART Control Registers
0x400D_0000 – 0x400D_3FFF	CMP_BA	Analog Comparator Control Registers
0x400E_0000 – 0x400E_3FFF	ADC_BA	Analog-Digital-Converter (ADC) Control Registers
<b>System Controllers Space (0xE000_E000 – 0xE000_EFFF)</b>		
0xE000_E010 – 0xE000_E0FF	SCS_BA	System Timer Control Registers
0xE000_E100 – 0xE000_ECFF	SCS_BA	Nested Vectored Interrupt Control Registers
0xE000_ED00 – 0xE000_ED8F	SCB_BA	System Control Block Registers

Table 5.1-1 Address Space Assignments for On-Chip Modules

## 5.2 Nested Vectored Interrupt Controller (NVIC)

### 5.2.1 Overview

The Cortex™-M0 CPU provides an interrupt controller as an integral part of the exception mode, named “Nested Vectored Interrupt Controller (NVIC)”. It is closely coupled to the processor kernel and provides the following features.

### 5.2.2 Features

- Nested and Vectored interrupt support
- Automatic processor state saving and restoration
- Dynamic priority change
- Reduced and deterministic interrupt latency

The NVIC prioritizes and handles all supported exceptions. All exceptions are handled in “Handler mode”. This NVIC architecture supports 32 (IRQ[31:0]) discrete interrupts with 4 levels of priority. All of the interrupts and most of the system exceptions can be configured to different priority levels. When an interrupt occurs, the NVIC will compare the priority of the new interrupt to the current running one’s priority. If the priority of the new interrupt is higher than the current one, the new interrupt handler will override the current handler.

When an interrupt is accepted, the starting address of the Interrupt Service Routine (ISR) is fetched from a vector table in memory. There is no need to determine which interrupt is accepted and branch to the starting address of the correlated ISR by software. While the starting address is fetched, the NVIC will also automatically save the processor state including the registers “PC, PSR, LR, R0~R3, R12” to the stack. At the end of the ISR, the NVIC will restore the mentioned registers from stack and resume the normal execution. Thus it will take less and deterministic time to process the interrupt request.

The NVIC supports “Tail Chaining” which handles back-to-back interrupts efficiently without the overhead of states saving and restoration and therefore reduces delay time in switching to pending ISR at the end of current ISR. The NVIC also supports “Late Arrival” which improves the efficiency of concurrent ISRs. When a higher priority interrupt request occurs before the current ISR starts to execute (at the stage of state saving and starting address fetching), the NVIC will give priority to the higher one without delay penalty. Thus it advances the real-time capability.

For more detailed information, please refer to the “ARM® Cortex™-M0 Technical Reference Manual” and “ARM® v6-M Architecture Reference Manual”.

### 5.2.3 Exception Model and System Interrupt Map

The exception model supported by the NuMicro Mini51™ series is listed in the following table. Software can set four levels of priority on some of these exceptions as well as on all interrupts. The highest user-configurable priority is denoted as “0” and the lowest priority is denoted as “3”. The default priority of all the user-configurable interrupts is “0”. Note that the priority “0” is treated as the fourth priority on the system, after the three system exceptions “Reset”, “NMI” and “Hard

Exception Number	IRQ Number (Bit in Interrupt Registers)	Exception Name	Source IP	Exception Description	Power-down Wake-up
30	14	<b>SPI_INT</b>	SPI	SPI interrupt	No
31	15	-	-	-	
32	16	<b>GP5_INT</b>	GPIO	External signal interrupt from GPIO group P5 except P5.2	Yes
33	17	<b>HFIRC_TRIM_INT</b>	HFIRC	HFIRC trim interrupt	No
34	18	<b>I2C_INT</b>	I <sup>2</sup> C	I <sup>2</sup> C interrupt	No
35 ~ 40	19 ~ 24	-	-	-	
41	25	<b>ACMP_INT</b>	ACMP	Analog Comparator 0 or 1 interrupt	Yes
42 ~ 43	26 ~ 27	-	-	-	
44	28	<b>PWRWU_INT</b>	CLKC	Clock controller interrupt for chip wake-up from Power-down state	Yes
45	29	<b>ADC_INT</b>	ADC	ADC interrupt	No
46 ~ 47	30 ~ 31	-	-	-	

Table 5.2-2 System Interrupt Map

#### 5.2.4 Vector Table

When an interrupt is accepted, the processor will automatically fetch the starting address of the interrupt service routine (ISR) from a vector table in memory. For ARMv6-M, the vector table based address is fixed at 0x0000\_0000. The vector table contains the initialization value for the stack pointer on reset, and the entry point addresses for all exception handlers. The vector number on previous page defines the order of entries in the vector table associated with the exception handler entry as illustrated in the previous section.

Vector Table Word Offset (Bytes)	Description
0x00	Initial Stack Pointer Value
Exception Number × 0x04	Exception Entry Pointer using that Exception Number

Table 5.2-3 Vector Table Format



## 5.2.5 NVIC Operation

NVIC interrupts can be enabled or disabled by writing to their corresponding Interrupt Set-Enable or Interrupt Clear-Enable register bit-field. The registers use a write-1-to-enable and write-1-to-clear policy, and both registers reading back the current enabled state of the corresponding interrupts. When an interrupt is disabled, interrupt assertion will cause the interrupt to become Pending; however, the interrupt will not be activated. If an interrupt is Active when it is disabled, it remains in its Active state until cleared by reset or an exception return. Clearing the enable bit prevents new activations of the associated interrupt.

NVIC interrupts can be pended/un-pended using a complementary pair of registers to those used to enable/disable the interrupts, named the Set-Pending Register and Clear-Pending Register respectively. The registers use a write-1-to-enable and write-1-to-clear policy, both registers reading back the current pended state of the corresponding interrupts. The Clear-Pending Register has no effect on the execution status of an Active interrupt.

NVIC interrupts are prioritized by updating an 8-bit field within a 32-bit register (each register supporting four interrupts).

The general registers associated with the NVIC are all accessible from a block of memory in the System Control Space and will be described in the next section.

## 5.4 Clock Controller

### 5.4.1 Overview

The clock controller generates the clocks for the whole chip, including system clocks and all peripheral clocks. The clock controller also implements the power control function with the individually clock ON/OFF control, clock source selection and a 4-bit clock divider. The chip will not enter Power-down mode until CPU sets the power-down enable bit (PWR\_DOWN\_EN) and Cortex-M0 core executes the WFI instruction. After that, the chip enters Power-down mode and wait for wake-up interrupt source triggered to leave Power-down mode. In Power-down mode, the clock controller turns off the external crystal and internal 22.1184 MHz oscillator to reduce the overall system power consumption.

### 5.4.2 Clock Generator

The clock generator consists of 3 sources which are listed below:

- One external 12 MHz (HXT) or 32 KHz (LXT) crystal
- One internal 22.1184 MHz RC oscillator (HIRC)
- One internal 10 KHz oscillator (LIRC)

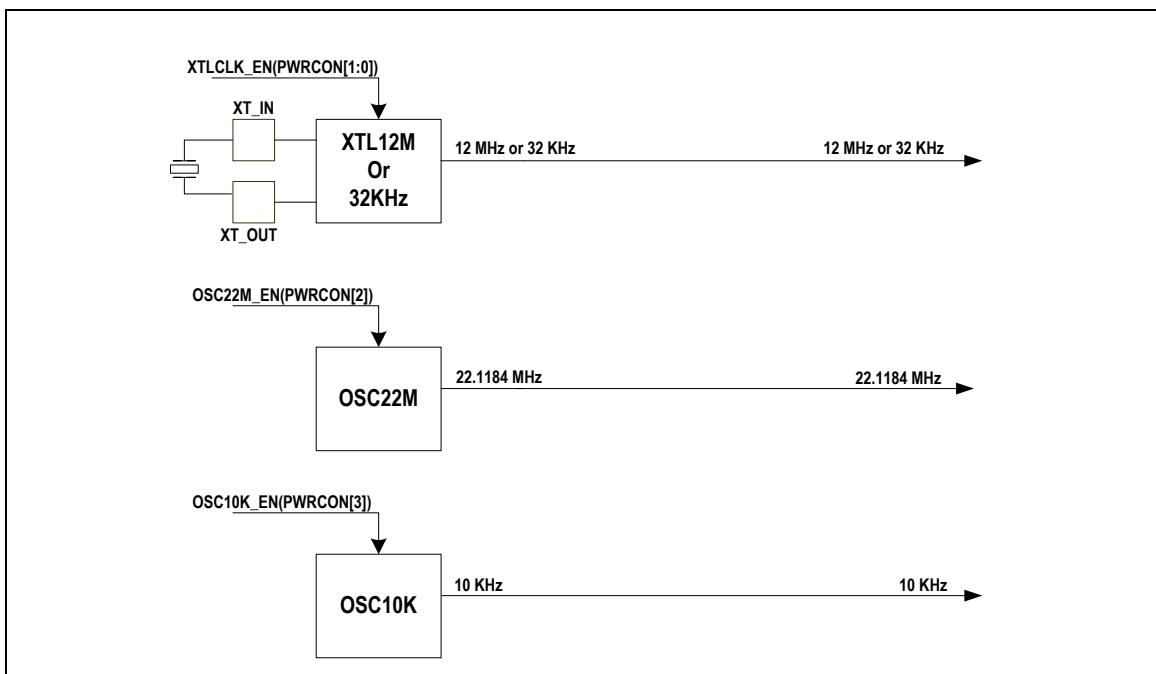


Figure 5.4-1 Clock Generator Block Diagram

### 5.4.4 AHB Clock Source Selection

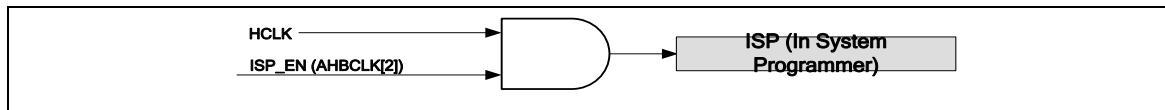


Figure 5.4-4 AHB Clock Source for HCLK

#### 5.4.7 Frequency Divider Output

This device is equipped with a power-of-2 frequency divider which is composed of 16 chained divide-by-2 shift registers. One of the 16 shift register outputs selected by a sixteen to one multiplexer is reflected to P3.6. Therefore, there are 16 options of power-of-2 divided clocks with the frequency from Fin/21 to Fin/217 where Fin is input clock frequency to the clock divider.

The output formula is  $F_{out} = Fin/2(N+1)$ , where Fin is the input clock frequency, Fout is the clock divider output frequency and N is the 4-bit value in FREQDIV.FSEL[3:0].

When FREQDIV.FDIV\_EN[4] is set to high, the rising transition will reset the chained counter and starts counting. When FREQDIV.FDIV\_EN[4] is written with zero, the chained counter continuously runs until the divided clock reaches low state and stays in low state.

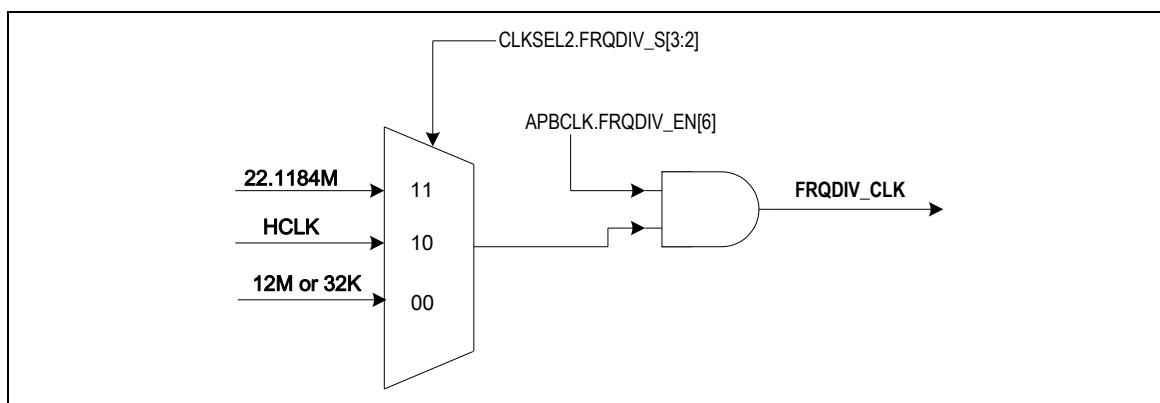


Figure 5.4-6 Clock Source of Frequency Divider

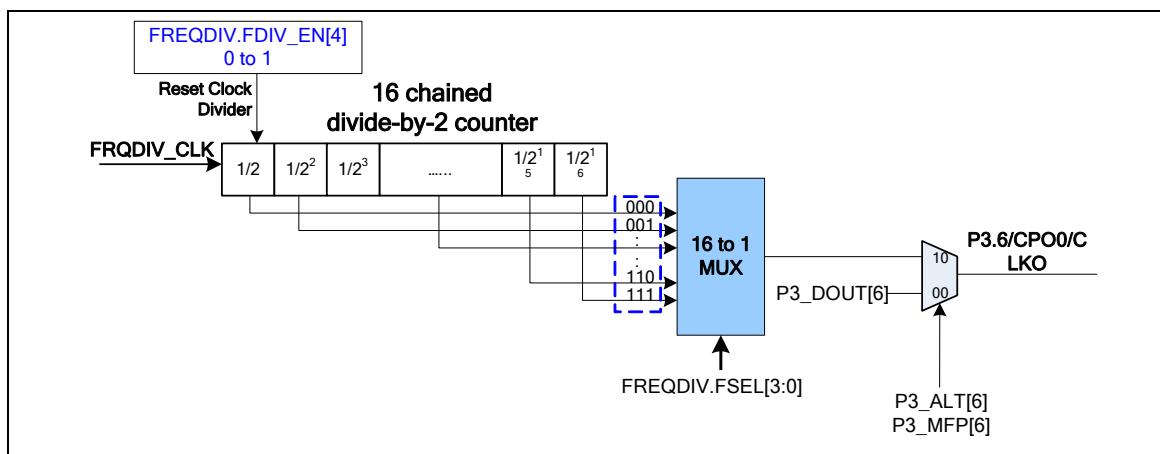


Figure 5.4-7 Block Diagram of Frequency Divider



## 5.7 Flash Memory Controller (FMC)

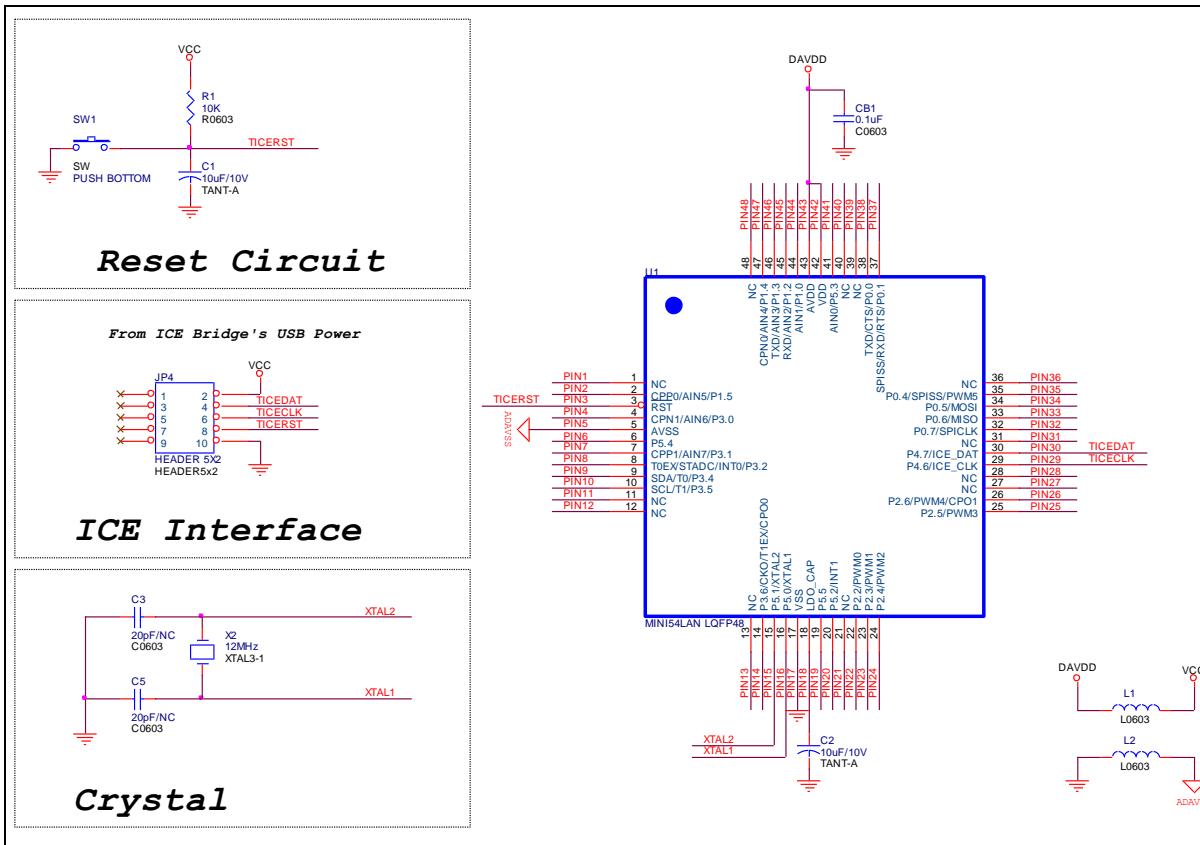
### 5.7.1 Overview

The NuMicro Mini51™ series is equipped with 4K/8K/16K bytes on chip embedded Flash EPROM for application program memory (APROM) that can be updated through ISP procedure. In System Programming (ISP) function enables user to update program memory when chip is soldered on PCB. After chip powered on Cortex-M0 CPU fetches code from APROM or LDROM decided by boot select (CBS) in Config0. By the way, the NuMicro Mini51™ series also provides DATA Flash Region, where the data flash is shared with original program memory and its start address is configurable and defined by user in Config1. The data flash size is defined by user depending on the application request.

### 5.7.2 Features

- Compatible with AHB interface
- Running up to 24 MHz with zero wait state for discontinuous address read access
- 4K/8K/16KB application program memory (APROM)
- 2KB in system programming (ISP) loader program memory (LDROM)
- Programmable data flash start address and memory size with 512 bytes page erase unit
- In System Program (ISP) to update on chip Flash EPROM

## 7 APPLICATION CIRCUIT



## 8.2 DC Electrical Characteristics

(VDD-VSS = 5.0 V, TA = 25°C, FOSC = 24 MHz unless otherwise specified.)

PARAMETER	Sym.	Specification				TEST CONDITIONS
		Min.	TYP.	Max.	Unit	
Operation voltage	V <sub>DD</sub>	2.5		5.5	V	V <sub>DD</sub> = 2.5 V ~ 5.5 V up to 24 MHz
V <sub>DD</sub> rise rate to ensure internal operation correctly	V <sub>RISE</sub>	0.05			V/mS	
Power ground	V <sub>SS</sub> AV <sub>SS</sub>	-0.3			V	
LDO output voltage	V <sub>LDO</sub>	-10%	1.8	+10%	V	V <sub>DD</sub> = 2.5V ~ 5.5V
Analog operating voltage	AV <sub>DD</sub>	0		V <sub>DD</sub>	V	
Operating current Normal run mode at 24 MHz	I <sub>DD1</sub>		9.5		mA	V <sub>DD</sub> = 5.5V at 24 MHz, all IP Enabled
	I <sub>DD2</sub>		7.5		mA	V <sub>DD</sub> = 5.5V at 24 MHz, all IP Disabled
	I <sub>DD3</sub>		7.5		mA	V <sub>DD</sub> = 3.3V at 24 MHz, all IP Enabled
	I <sub>DD4</sub>		6		mA	V <sub>DD</sub> = 3.3V at 24 MHz, all IP Disabled
Operating current Normal run mode at 12 MHz	I <sub>DD5</sub>		5.5		mA	V <sub>DD</sub> = 5.5V at 12 MHz, all IP Enabled
	I <sub>DD6</sub>		4.5		mA	V <sub>DD</sub> = 5.5V at 12 MHz, all IP Disabled
	I <sub>DD7</sub>		4		mA	V <sub>DD</sub> = 3.3V at 12 MHz, all IP Enabled
	I <sub>DD8</sub>		3		mA	V <sub>DD</sub> = 3.3V at 12 MHz, all IP Disabled
Operating current Normal run mode at 4 MHz	I <sub>DD9</sub>		3.6		mA	V <sub>DD</sub> = 5.5V at 4 MHz, all IP Enabled
	I <sub>DD10</sub>		3.3		mA	V <sub>DD</sub> = 5.5V at 4 MHz, all IP Disabled
	I <sub>DD11</sub>		1.7		mA	V <sub>DD</sub> = 3.3V at 4 MHz, all IP Enabled
	I <sub>DD12</sub>		1.4		mA	V <sub>DD</sub> = 3.3V at 4 MHz, all IP Disabled
Operating current Normal run mode at 22.1184 MHz IRC	I <sub>DD13</sub>		6.6		mA	V <sub>DD</sub> = 5.5V at 22.1184 MHz, all IP Enabled
	I <sub>DD14</sub>		5		mA	V <sub>DD</sub> = 5.5V at 22.1184 MHz, all IP Disabled
	I <sub>DD15</sub>		6.6		mA	V <sub>DD</sub> = 3.3V at 22.1184 MHz, all IP Enabled
	I <sub>DD16</sub>		5		mA	V <sub>DD</sub> = 3.3V at 22.1184 MHz, all IP Disabled

PARAMETER	Sym.	Specification				TEST CONDITIONS
		Min.	TYP.	Max.	Unit	
Operating current Normal run mode at 32.768 KHz crystal oscillator	I <sub>DD17</sub>		116		µA	V <sub>DD</sub> = 5.5V at 32.768 KHz, all IP Enabled
	I <sub>DD18</sub>		113		µA	V <sub>DD</sub> = 5.5V at 32.768 KHz, all IP Disabled
	I <sub>DD19</sub>		112		µA	V <sub>DD</sub> = 3.3V at 32.768 KHz, all IP Enabled
	I <sub>DD20</sub>		100		µA	V <sub>DD</sub> = 3.3V at 32.768 KHz, all IP Disabled
Operating current Normal run mode at 10 KHz IRC	I <sub>DD21</sub>		109		µA	V <sub>DD</sub> = 5.5V at 10 KHz, all IP Enabled
	I <sub>DD22</sub>		108		µA	V <sub>DD</sub> = 5.5V at 10 KHz, all IP Disabled
	I <sub>DD23</sub>		100		µA	V <sub>DD</sub> = 3.3V at 10 KHz, all IP Enabled
	I <sub>DD24</sub>		98		µA	V <sub>DD</sub> = 3.3V at 10 KHz, all IP Disabled
Operating current Idle mode at 24 MHz	I <sub>IDLE1</sub>		5.5		mA	V <sub>DD</sub> = 5.5V at 24 MHz, all IP Enabled
	I <sub>IDLE2</sub>		3.5		mA	V <sub>DD</sub> = 5.5V at 24 MHz, all IP Disabled
	I <sub>IDLE3</sub>		3.8		mA	V <sub>DD</sub> = 3.3V at 24 MHz, all IP Enabled
	I <sub>IDLE4</sub>		1.8		mA	V <sub>DD</sub> = 3.3V at 24 MHz, all IP Disabled
Operating current Idle mode at 12 MHz	I <sub>IDLE5</sub>		3.3		mA	V <sub>DD</sub> = 5.5V at 12 MHz, all IP Enabled
	I <sub>IDLE6</sub>		2.6		mA	V <sub>DD</sub> = 5.5V at 12 MHz, all IP Disabled
	I <sub>IDLE7</sub>		2		mA	V <sub>DD</sub> = 3.3V at 12 MHz, all IP Enabled
	I <sub>IDLE8</sub>		1		mA	V <sub>DD</sub> = 3.3V at 12 MHz, all IP Disabled
Operating current Idle mode at 4 MHz	I <sub>IDLE9</sub>		3		mA	V <sub>DD</sub> = 5.5V at 4 MHz, all IP Enabled
	I <sub>IDLE10</sub>		2.3		mA	V <sub>DD</sub> = 5.5V at 4 MHz, all IP Disabled
	I <sub>IDLE11</sub>		1		mA	V <sub>DD</sub> = 3.3V at 4 MHz, all IP Enabled
	I <sub>IDLE12</sub>		0.7		mA	V <sub>DD</sub> = 3.3V at 4 MHz, all IP Disabled
Operating current Idle mode at 22.1184 MHz IRC	I <sub>IDLE13</sub>		3.0		mA	V <sub>DD</sub> = 5.5V at 22.1184 MHz, all IP Enabled
	I <sub>IDLE14</sub>		1.2		mA	V <sub>DD</sub> = 5.5V at 22.1184 MHz, all IP Disabled
	I <sub>IDLE15</sub>		3.0		mA	V <sub>DD</sub> = 3.3V at 22.1184 MHz, all IP Enabled

Figure 8.3-1 Typical Crystal Application Circuit

### 8.3.4 External 32.768 KHz XTAL Oscillator

PARAMETER	Sym.	Specification				TEST CONDITIONS
		Min.	TYP.	Max.	Unit	
Oscillator frequency	$f_{L_{XTAL}}$		32.768		KHz	$V_{DD} = 2.5V \sim 5.5V$
Temperature	$T_{L_{XTAL}}$	-40		+85	°C	
Operating current	$I_{HXTAL}$		TBD		μA	$V_{DD} = 5.0V$

### 8.3.5 Internal 22.1184 MHz RC Oscillator

PARAMETER	Sym.	Specification				TEST CONDITIONS
		Min.	TYP.	Max.	Unit	
Supply voltage <sup>[1]</sup>	$V_{HRC}$		1.8		V	
Center frequency	$F_{HRC}$	21.89	22.1184	22.34	MHz	$25^{\circ}C, V_{DD} = 5V$
		20.57	22.1184	23.23	MHz	$-40^{\circ}C \sim +85^{\circ}C, V_{DD} = 2.5V \sim 5.5V$
		21.78	22.0	22.22	MHz	$-40^{\circ}C \sim +85^{\circ}C, V_{DD} = 2.5V \sim 5.5V$ 32.768K crystal oscillator Enabled and TRIM_SEL = 1
Operating current	$I_{HRC}$		TBD		mA	

Note: Internal operation voltage comes from LDO.

### 8.3.6 Internal 10 KHz RC Oscillator

PARAMETER	Sym.	Specification				TEST CONDITIONS
		Min.	TYP.	Max.	Unit	
Supply voltage <sup>[1]</sup>	$V_{LRC}$		1.8		V	
Center frequency	$F_{LRC}$	7	10	13	KHz	$25^{\circ}C, V_{DD} = 5V$
		5	10	15	KHz	$-40^{\circ}C \sim +85^{\circ}C, V_{DD} = 2.5V \sim 5.5V$
Operating current	$I_{LRC}$		TBD		μA	$V_{DD} = 5V$

Note: Internal operation voltage comes from LDO.

**8.4.6 Flash Memory Characteristics**

PARAMETER	Sym.	Specification				TEST CONDITIONS
		Min.	TYP.	Max.	Unit	
Cycling (erase/write) Program memory	N <sub>CYC</sub>	100			K cycle	
Data retention	T <sub>RET</sub>	10			years	T <sub>A</sub> = +85°C
Erase time of ISP mode	T <sub>ERASE</sub>	2.3	2.5	2.7	μS	Erase time for one page
Program time of ISP mode	T <sub>PROG</sub>	57	62	67	μS	Programming time for one word
Program current	I <sub>PROG</sub>		3.3		mA	V <sub>DD</sub> = 5.5V

## 9 PACKAGE DIMENSION

### 9.1 48-pin LQFP

